
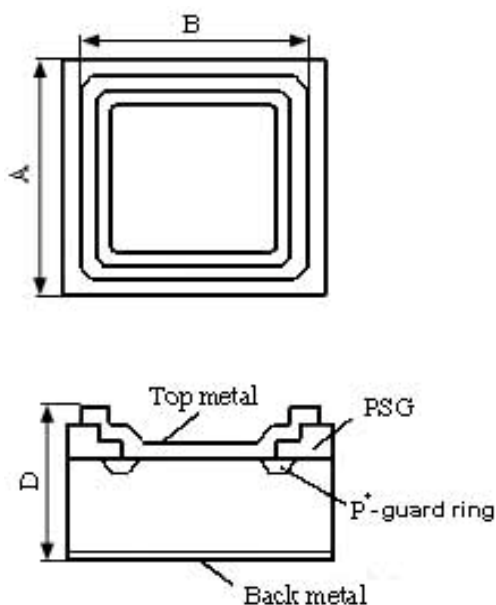


		10A/30V.Die Size-106*158mil. 		
Electrical Characteristics	Symbol	Unit	Spec. Limit	Die Sort
Breakdown Voltage @ I _R =10mA	V _B	V	30	35
Average Rectified Forward Current	I _{F(AV)}	A	10,0	-
DC Forward Voltage @ 25°C, I _F =10,0A	V _F	V	0,42	0,40
Maximum Reverse Current @ 25°C, V _R =35V @ 25°C, V _R =30V @ 125°C, V _R =30V	I _R	mA	- 0,400 150,0	0,400 0,300 140,0
Peak Forward Surge Current 8,3ms single half sine-wave superimposed on rated load (JEDEC METHOD)	I _{FSM}	A	300	-
Peak Repetitive Reverse Surge Current @2,0μs, f=1kHz., T _J <150°C.	I _{RRM}	A	5,0	
Electrostatic Discharge Voltage. JEDEC Method. ESD HBM. Contact.	V _{ESD}	kV	±8 (contact)	
Voltage Rate of Change	dV/dt	V/μS	10.000	
Operating Junction Temperature	T _J	°C	150	



DIM	ITEM	μm
A _X A _Y	Die Size	2700 4000
B _X B _Y	Top Metal Size	2560 3860
D	Thickness	300max.
Scribe line Width		80

Top metal:
 a) Ti-Ni-Ag – for Soldering;
 b) Al.- for Wire Bonding.
 Back metal: Ti-Ni-Ag.